



Description

Polypropylene Aceso® PPM H250 S01 is narrow molecular weight distribution homopolymer with a Melt Flow Index of 25g/10 min recommended for the manufacture of medical packaging and medical devices, to the exclusion of implants.

Polypropylene Aceso® PPM H250 S01 is the version of the Polypropylene Aceso® PPM H250 based on a phthalate-free catalyst.

Characteristics

	Method	Unit	Typical Value
Rheological properties			
Melt Flow Index 230°C/2.16 kg	ISO 1133	g/10 min	25
Mechanical properties			
Tensile Strength at Yield	ISO 527-2	MPa	32
Elongation at Yield	ISO 527-2	%	<10
Tensile modulus	ISO 527-2	MPa	1350
Flexural modulus	ISO 178	MPa	1250
Izod Impact Strength (notched) at 23°C	ISO 180	kJ/m ²	3.5
Charpy Impact Strength (notched) at 23°C	ISO 179	kJ/m ²	5
Hardness Rockwell - R-scale	ISO 2039-2		90
Thermal properties			
Melting Point	ISO 3146	°C	165
Vicat Softening Point	ISO 306	°C	
50N-50°C per hour			80
10N-50°C per hour			148
Heat Deflection Temperature	ISO 752	°C	
1.80 MPa - 120°C per hour			52
0.45 MPa - 120°C per hour			95
Other physical properties			
Density	ISO 1183	g/cm ³	0.905
Bulk Density	ISO 1183	g/cm ³	0.525

Handling and storage

Please refer to the safety data sheet (SDS) for handling and storage information. It is advisable to convert the product within one year after delivery provided storage conditions are used as given in the SDS of our product. SDS may be obtained from the website: <http://www.totalrefiningchemicals.com>

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